Modern Electroplating, Fifth Edition

Members will Receive a Discount!

The definitive resource for electroplating, now completely up to date

Edited by
MORDECHAY SCHLESINGER, University of Windsor, Ontario, Canada
and MILAN PAUNOVIC

978-0-470-16778-6 / 736 pages / Hardcover / September 2010

With advances in information-age technologies, the field of electroplating has seen dramatic growth in the decade since the previous edition of Modern Electroplating was published. This expanded new edition addresses these developments, providing a comprehensive, one-stop reference to the latest methods and applications of electroplating of metals, alloys, semiconductors, and conductive polymers. With special emphasis on electroplating and electrochemical plating in nanotechnologies, data storage, and medical applications, the Fifth Edition boasts vast amounts of new and revised material, unmatched in breadth and depth by any other book on the subject. It includes:

- Easily accessible, self-contained contributions by over thirty experts
- Five completely new chapters and hundreds of additional pages
- A cutting-edge look at applications in nanoelectronics
- Coverage of the formation of nanoclusters and quantum dots using scanning tunneling microscopy (STM)
- An important discussion of the physical properties of metal thin films
- Chapters devoted to methods, tools, control, and environmental issues
- And much more

A must-have for anyone in electroplating, including technicians, platers, plating researchers, and metal finishers, Modern Electroplating, Fifth Edition is also an excellent reference for electrical engineers and researchers in the automotive, data storage, and medical industries.

About the Editor

MORDECHAY SCHLESINGER, PhD, is a professor in the Department of Physics at the University of Windsor, Ontario, Canada. He has published over 120 research papers, holds four patents, and has served as associate editor for the Journal of The Electrochemical Society, Electrochemical and Solid-State Letters, and as coeditor of the Canadian Journal of Physics. Schlesinger is coauthor, with Milan Paunovic, of the first and second editions of Fundamentals of Electrochemical Deposition and the previous edition of Modern Electroplating (both by Wiley).

MILAN PAUNOVIC, PhD, had, until his recent retirement, worked on electrochemical metal deposition for over four decades, most recently in the Electrodeposition Technology Department at IBM’s T. J. Watson Research Center, and previously at the University of Pennsylvania, Reynolds Metals, Kollmorgen, and Intel. In addition to coauthoring, with Mordechay Schlesinger, the first and second editions of Fundamentals of Electrochemical Deposition and the previous edition of Modern Electroplating, Dr. Paunovic has edited symposia proceedings for The Electrochemical Society, published forty-one research papers, and holds seven patents.

TO ORDER call 609.737.1902 or visit the ECS website at www.electrochem.org